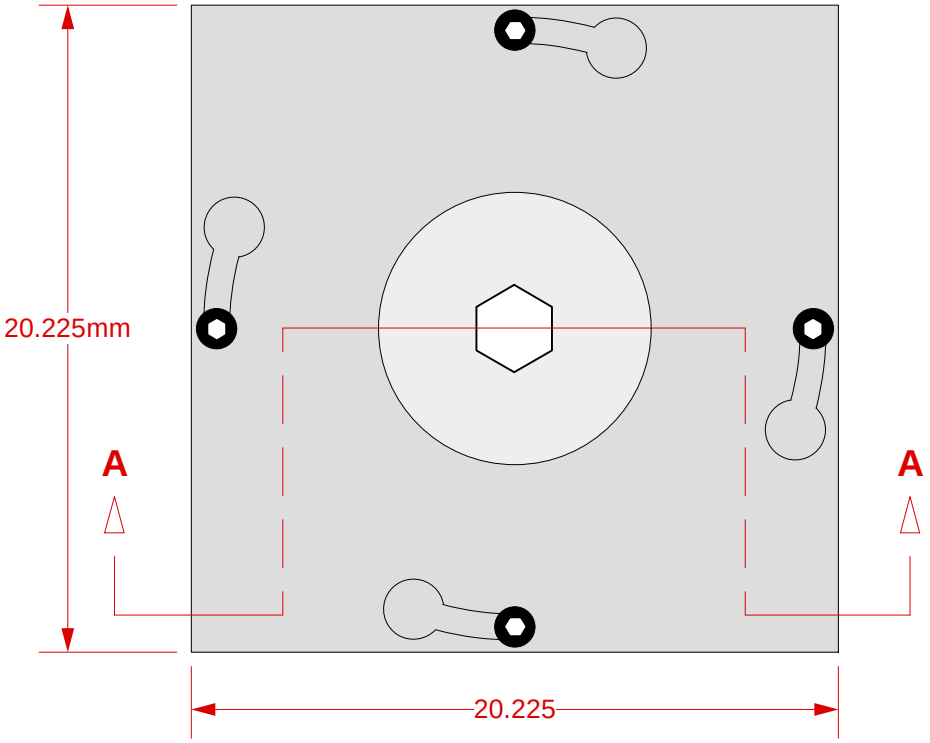
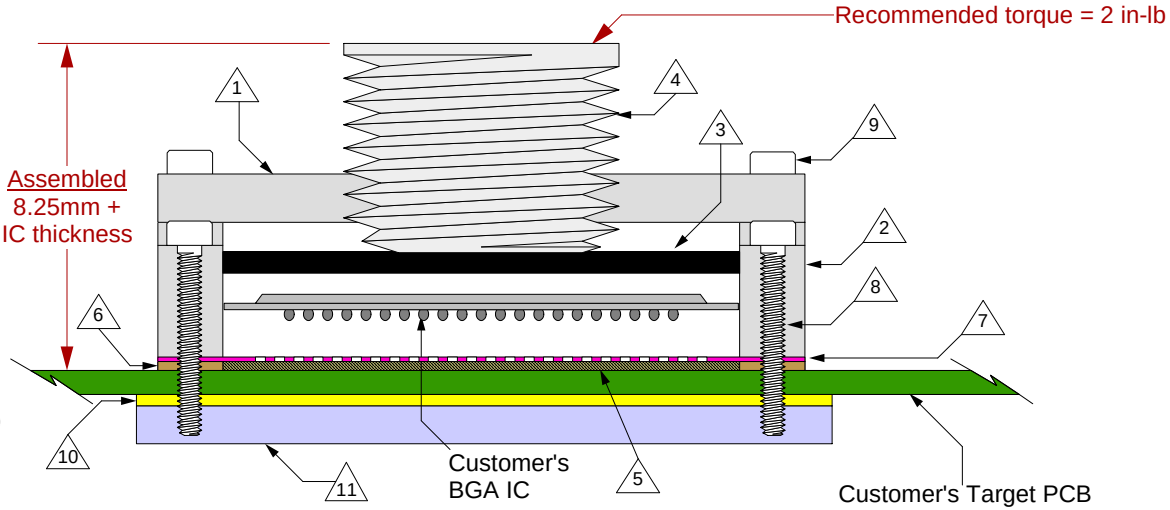
GHz BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid



Top View



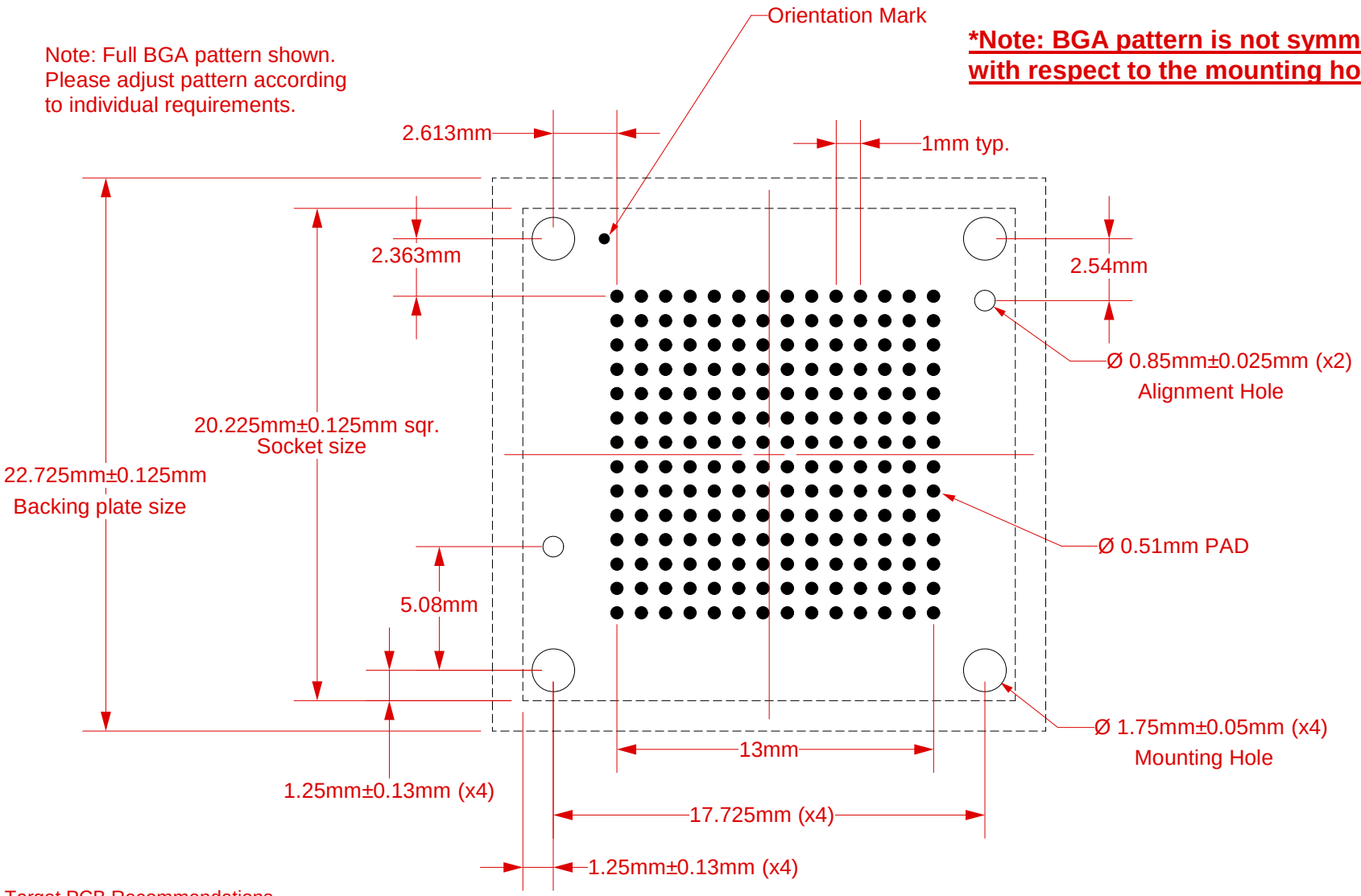
Side View
(Section AA)

1. Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
2. Socket base: Black anodized Aluminum. Thickness = 5mm.
3. Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
4. Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
5. Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
6. Elastomer Guide: Non-clad FR4. Thickness = 0.475mm.
7. Ball Guide: Kapton polyimide.
8. Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread , 15.875mm long.
9. Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
10. Insulation Plate: FR4/G10, Thickness = 1.59mm.
11. Backing Plate: Black anodized Aluminum. Thickness = 6.35mm.

SG-BGA-8006 Drawing	Status: Released	Scale: -	Rev: B
 11351 Rupp Dr. Suite 400, Burnsville MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: J. Glab	Date: 07/30/07	
	File: SG-BGA-8006 Dwg.mcd	Modified: 7/2/09, AE	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View



Target PCB Recommendations
Total thickness: 1.6mm min.
Plating: Gold or Solder finish.
PCB pad height: Same or higher than solder mask.

NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

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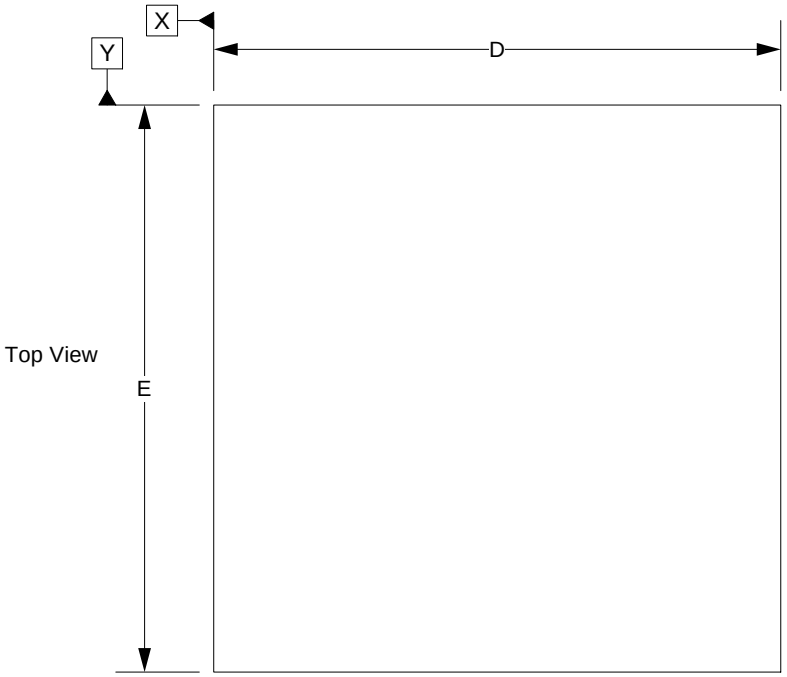

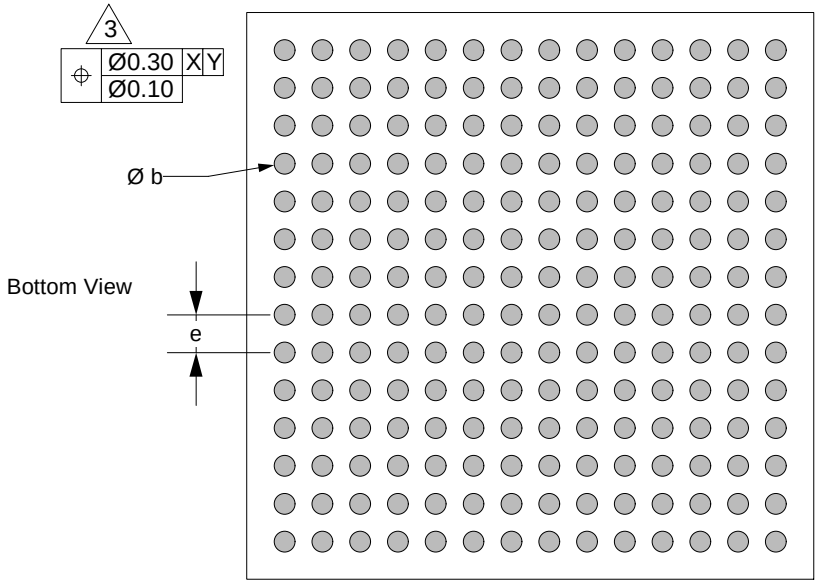

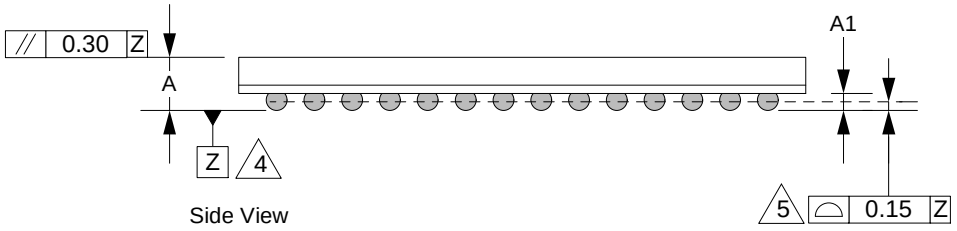

1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A	1.32	1.75
A1	0.27	0.47
b	0.35	0.65
D	15.0 BSC	
E	15.0 BSC	
e	1.0 BSC	

Array:14x14

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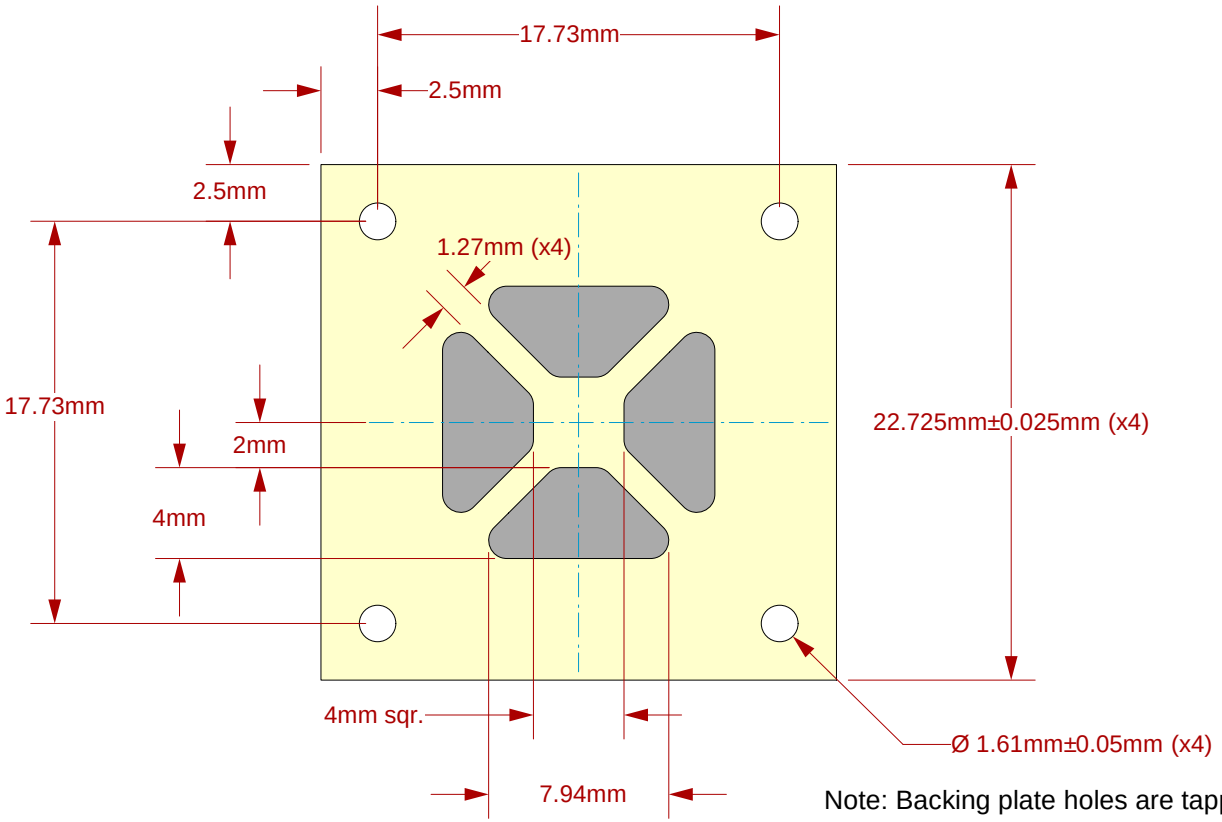
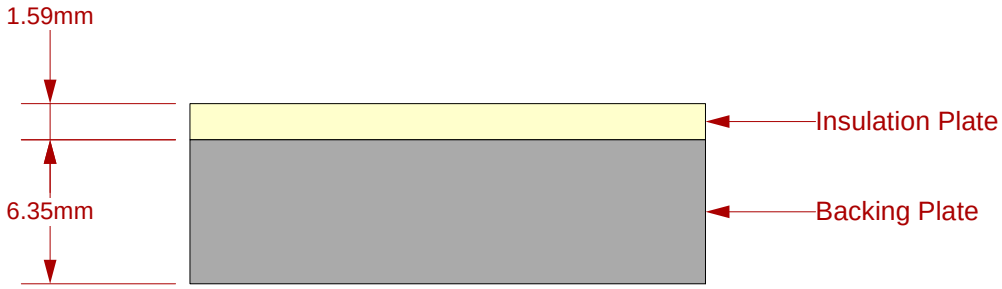
Backing Plate

Top View



Front View



Note: Backing plate holes are tapped to accept 0-80 screws.

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